

Title (en)  
Insert-molded electrical connector and method of manufacture

Title (de)  
Eingegossener elektrischer Steckverbinder und Herstellungsverfahren

Title (fr)  
Connecteur électrique surmoulé et méthode de fabrication

Publication  
**EP 1063738 A1 20001227 (EN)**

Application  
**EP 00113238 A 20000621**

Priority  
JP 17599799 A 19990622

Abstract (en)  
An electrical connector (10) is provided having a plurality of conductive terminals(15) insert-molded with a housing (30). Each of the terminals (14) has a reduced-thickness tip portion (40) having a stepped profile (42). The stepped profile (42) has a non-curved corner that meets an exposed contact surface (38) of the terminal (14). The corner of the terminal remains positioned against a wall of a mold cavity during the insert-molding process but permits the tip portion (40) to be embedded in the housing material for secure mounting. The terminal advantageously avoids the formation of a burr or resin film on the exposed contact surface (38) during insert-molding. Such a connector is useful, for example, in miniature size connector applications wherein the terminals are small and lack significant rigidity needed to permit easy assembly with a pre-formed housing.  
<IMAGE>

IPC 1-7  
**H01R 43/24**; **H01R 43/16**

IPC 8 full level  
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CPC (source: EP)  
**H01R 43/24** (2013.01); **H01R 13/405** (2013.01); **H01R 43/16** (2013.01)

Citation (search report)  
• [XAY] US 5201883 A 19930413 - ATOH KIYOSHI [JP], et al  
• [Y] DE 4419293 A1 19950420 - FUJITSU LTD [JP]  
• [X] US 3943625 A 19760316 - BRENNAN ROBERT R, et al  
• [A] US 3987264 A 19761019 - SEIDLER JACK

Cited by  
DE10393763B4; CN110364914A; WO2012145194A3

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